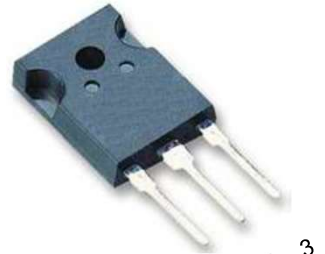
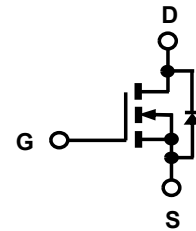


ICE16M120W Silicon Carbide Power MOSFET

Features

- 1200V 16mohm SiC MOSFET
- Low on-resistance
- Fast switching speed with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- Optimized design for high performance power systems

Product Summary			
I_D	$T_A=25^\circ\text{C}$	112A	Max
$V_{(BR)DSS}$	$T_C=25^\circ\text{C}$	1200V	Min
$r_{DS(on)}$	$V_{GS}=18\text{V}$	16m Ω	Typ
Q_g	$V_{DS}=800\text{V}$	279nC	Typ



TO247
1:G, 2:D,
3:S
(TO-247)



Lead Free

Maximum ratings^a, at $T_j=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_c=25^\circ\text{C}$	112	A
		$T_c=100^\circ\text{C}$	79	
Pulsed drain current	$I_{D, \text{pulse}}$		275	A
Maximum gate source voltage	$V_{GS(max)}$		-10/+22	V
Operational gate source voltage	$V_{GS \text{ op}}$		-6/+18	V
Power dissipation	P_{tot}		500	W
Storage temperature	T_{stg}		-55 to +175	$^\circ\text{C}$
Operating temperature	T_j			

^a Pulse width limited by T_{jmax}

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

Thermal characteristics

Thermal resistance, junction-case	R_{thJC}		-	-	0.3	°C/W
Thermal resistance, junction-ambient	R_{thJA}	leaded	-	-	40	
Soldering temperature, wave soldering only allowed at leads	T_{solder}	1.6mm (0.063in.) from case for 10 s	-	-	260	°C

Electrical characteristics^a, at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=100\mu A$	1200	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=23mA, T_j=25^{\circ}\text{C}$	1.8	2.6	4	
		$V_{DS}=V_{GS}, I_D=23mA, T_j=175^{\circ}\text{C}$	-	1.8	-	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=1200V, V_{GS}=0V$	-	5	50	μA
Gate source leakage current	I_{GSS}	$V_{GS}=-10/+22V, V_{DS}=0V$	-	-	± 100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=18V, I_D=75A, T_j=25^{\circ}\text{C}$	-	16	22	m Ω
		$V_{GS}=18V, I_D=75A, T_j=175^{\circ}\text{C}$	-	29	-	
Gate resistance	R_G	$f=1\text{ MHz}, V_{AC}=25mV$	-	6.5	-	Ω

Dynamic characteristics

Input capacitance	C_{iss}	$V_{DS}=800V, V_{GS}=0V, f=100\text{ kHz}, V_{AC}=25mV$	-	5800	-	pF
Output capacitance	C_{oss}		-	213	-	
Reverse transfer capacitance	C_{rss}		-	16	-	
C_{OSS} stored energy	E_{oss}		-	85	-	μJ
Forward transconductance	g_{FS}	$V_{DS}=30V, I_D=75A$	-	44	-	S
Turn-on delay time	$t_{d(on)}$	$V_{DS}=800V, V_{GS}=-4/+18V, I_D=75A, R_G=2.5\Omega$ (External), $L=100\mu H, T_j=25^{\circ}\text{C}$	-	35	-	ns
Rise time	t_r		-	44	-	
Turn-off delay time	$t_{d(off)}$		-	149	-	
Fall time	t_f		-	37	-	
Turn-on switching energy	E_{ON}	Diode: Body Diode at $V_{GS}=-4V$	-	1733	-	μJ
Turn-off switching energy	E_{OFF}		-	1540	-	

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

Dynamic characteristics

Turn-on delay time	$t_{d(on)}$	$V_{DS}=800V, V_{GS}=-4/+18V,$ $I_D=75A, R_G=2.5\Omega$ (External), $L=100\mu H,$ $T_j=175^\circ C$	-	33	-	ns
Rise time	t_r		-	47	-	
Turn-off delay time	$t_{d(off)}$		-	203	-	
Fall time	t_f		-	40	-	
Turn-on switching energy	E_{ON}	Diode: Body Diode at $V_{GS}=-4V$ $T_j=175^\circ C$	-	1992	-	μJ
Turn-off switching energy	E_{OFF}		-	1790	-	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DS}=800V, I_D=75A,$ $V_{GS}=-4$ to $+18V$	-	65	-	nC
Gate to drain charge	Q_{gd}		-	81	-	
Gate charge total	Q_g		-	279	-	

Reverse Diode

Continuous forward current	I_S	$V_{GS}=-4V$	-	-	112	A
Diode forward voltage	V_{SD}	$V_{GS}=-4V, I_{SD}=37.5A,$ $T_j=25^\circ C$	-	5.3	-	V
		$V_{GS}=-4V, I_{SD}=37.5A,$ $T_j=175^\circ C$	-	4.8	-	
Reverse recovery time	t_{rr}	$V_{GS}=-4V, V_{RR}=800V,$ $I_{SD}=75A,$ $d_i f/d_t=2600 A/\mu s$	-	33	-	ns
Reverse recovery charge	Q_{rr}		-	842	-	nC
Peak reverse recovery current	I_{rm}		-	45	-	A

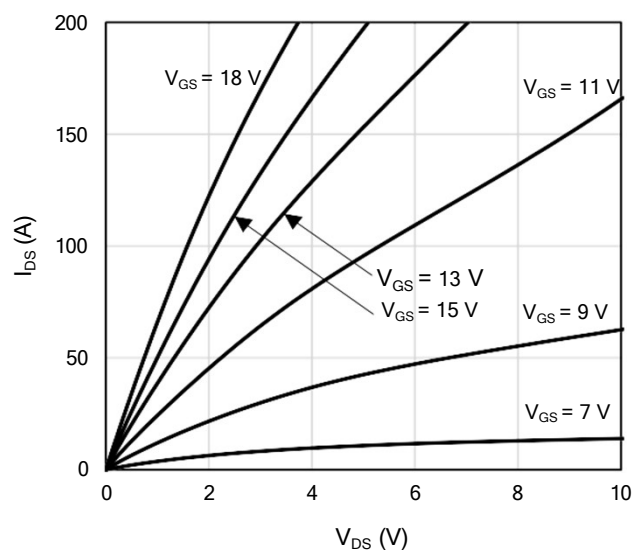


Figure 1: Output Characteristics $T_J = -40^\circ\text{C}$

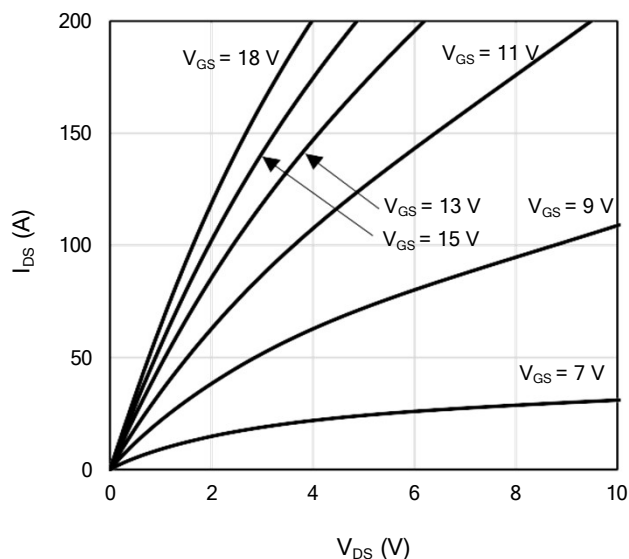


Figure 2: Output Characteristics $T_J = 25^\circ\text{C}$

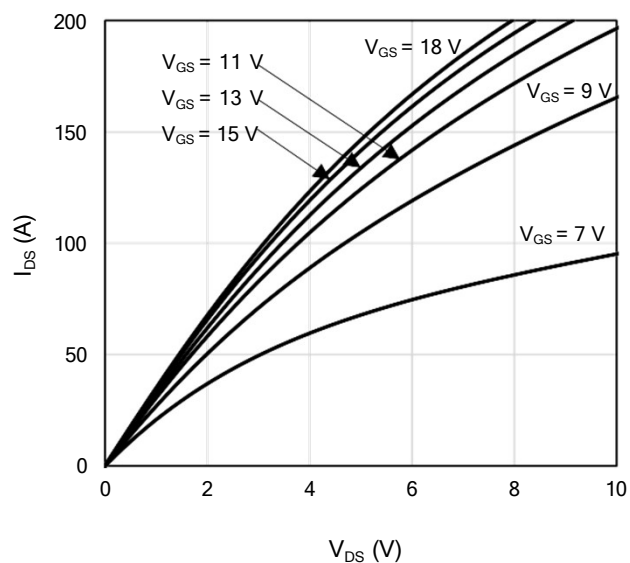


Figure 3: Output Characteristics $T_J = 175^\circ\text{C}$

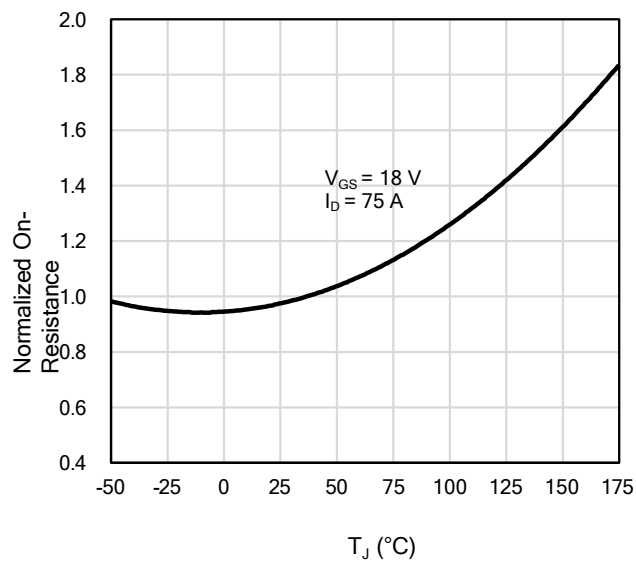


Figure 4: Normalized On-Resistance vs. Temperature

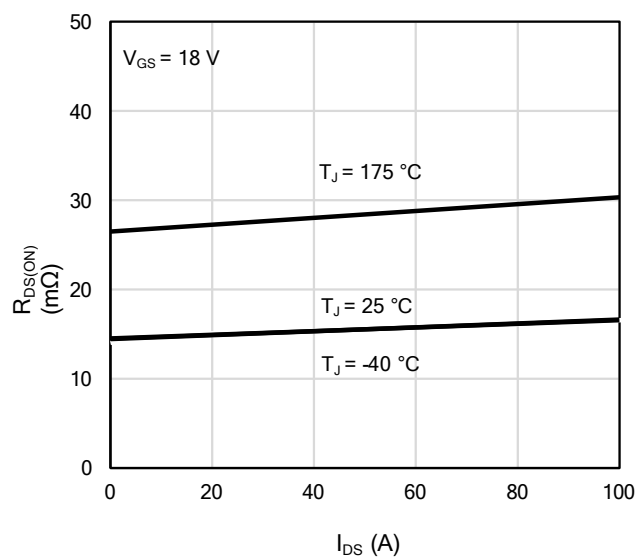


Figure 5: On-Resistance vs. Drain Current
For Various Temperatures

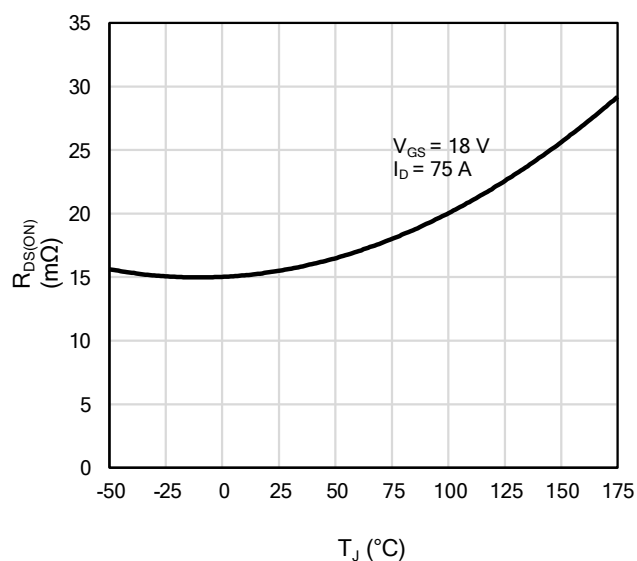


Figure 6: On-Resistance vs. Temperature

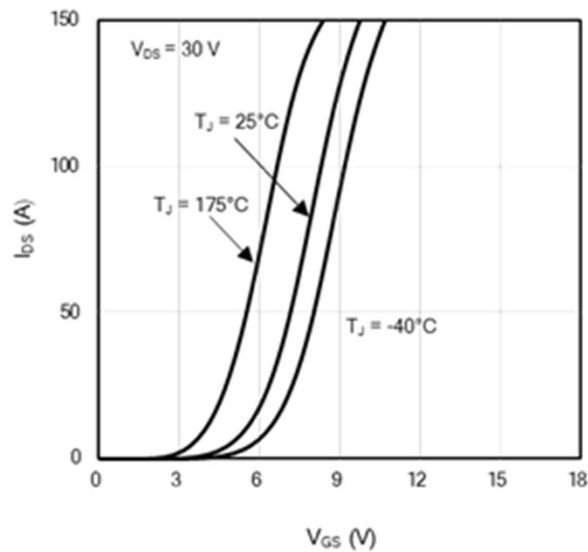


Figure 7: Transfer Characteristics For Various Junction Temperatures

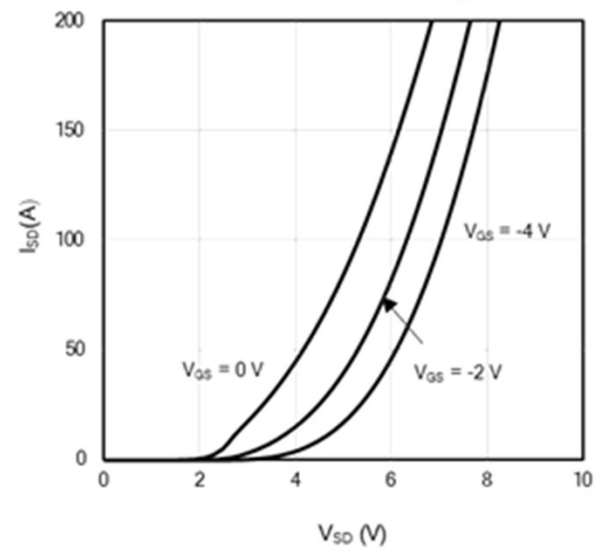


Figure 8: Body Diode Characteristics at -40°C

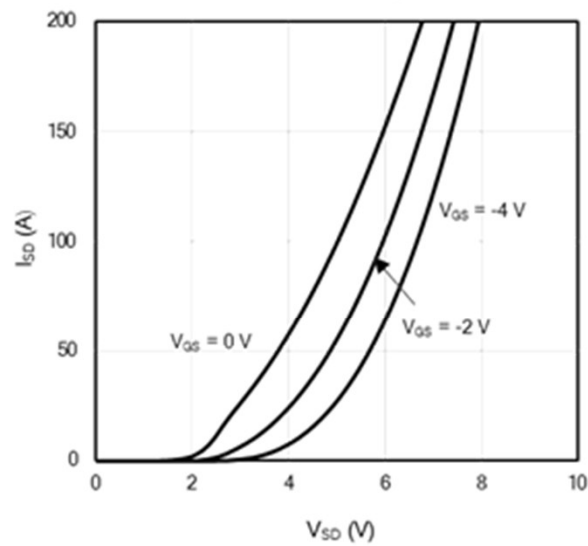


Figure 9: Body Diode Characteristics at 25°C

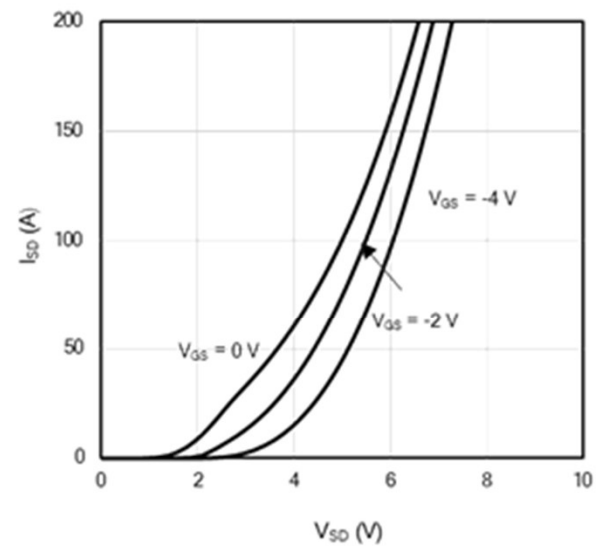


Figure 10: Body Diode Characteristics at 175°C

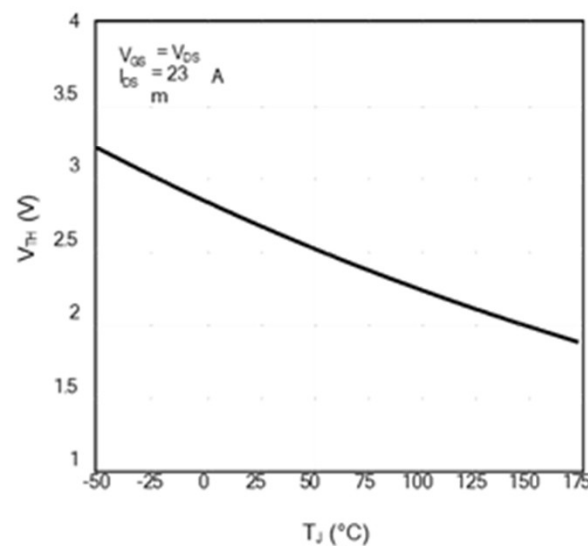


Figure 11: Threshold Voltage vs. Temperature

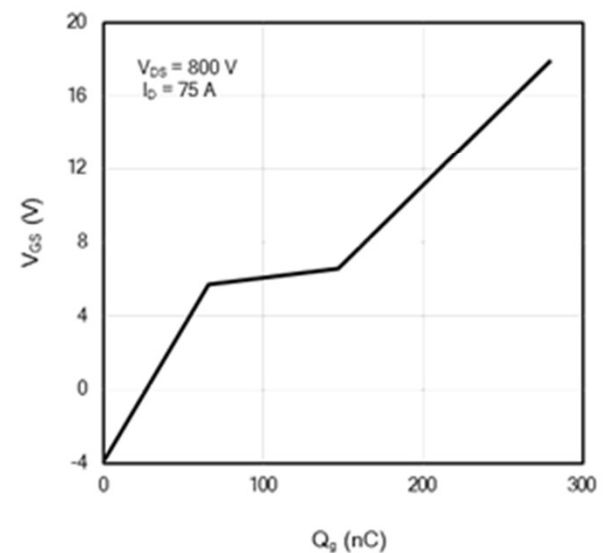


Figure 12: Gate-Charge Characteristics

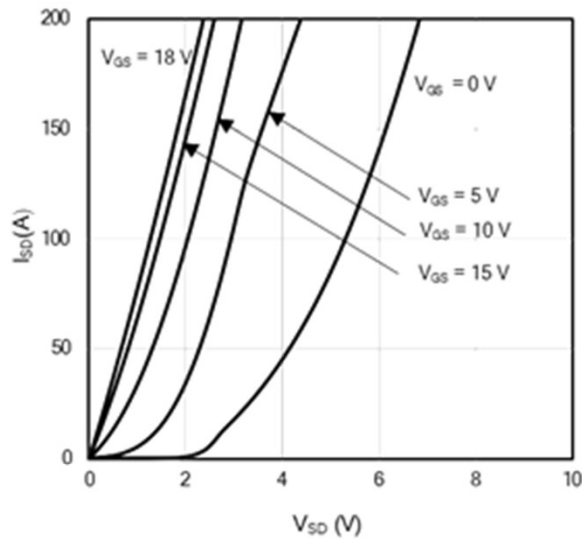


Figure 13: 3rd Quadrant Characteristics at -40°C

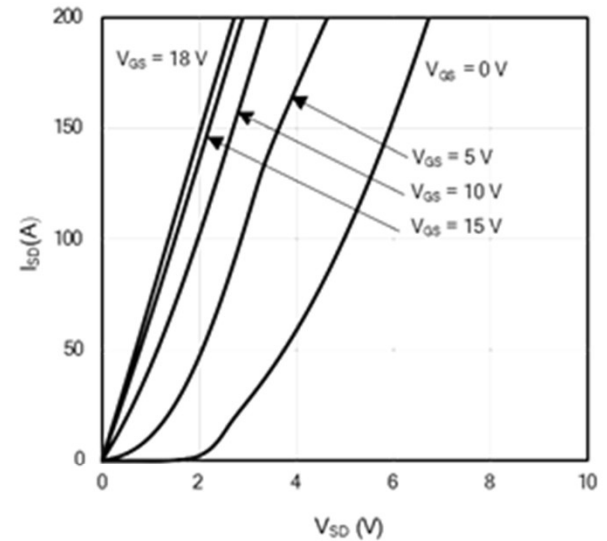


Figure 14: 3rd Quadrant Characteristics at 25°C

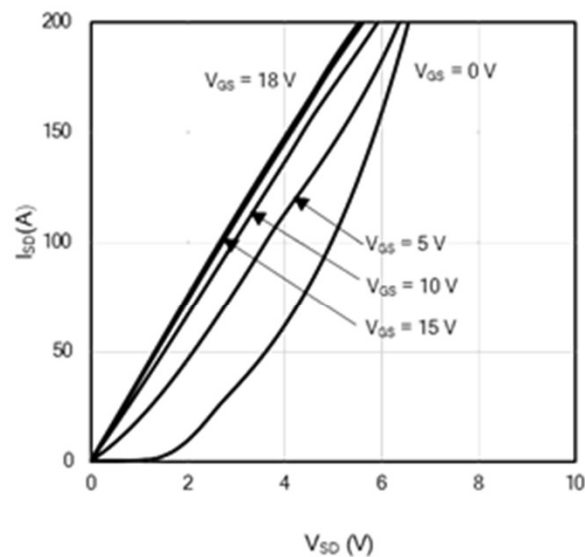


Figure 15: 3rd Quadrant Characteristics at 175°C

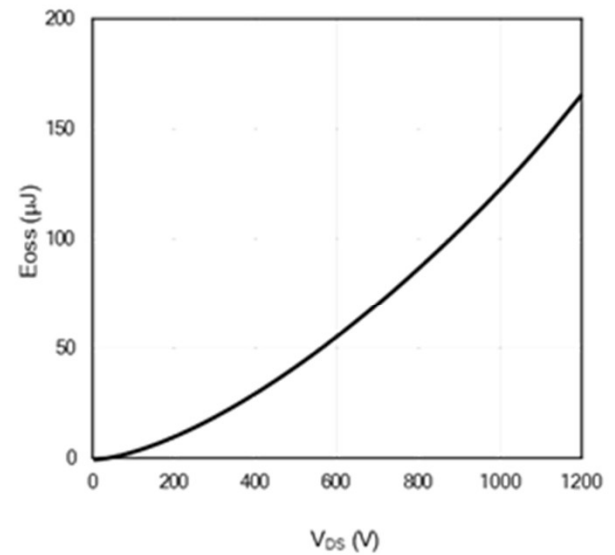


Figure 16: Output Capacitor Stored Energy

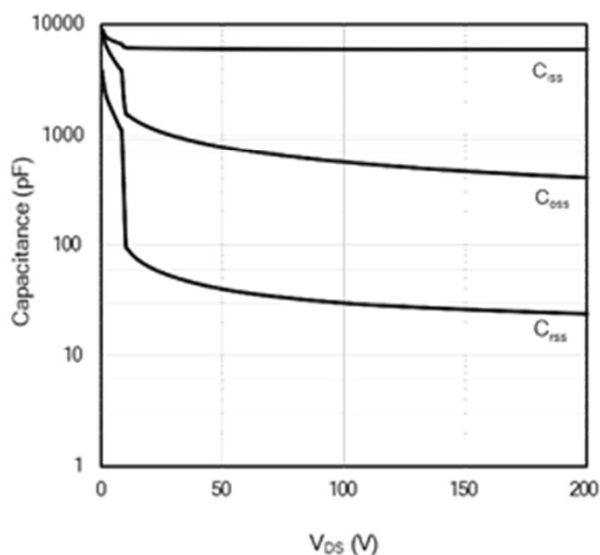


Figure 17: Capacitance Characteristics (0 - 200 V)

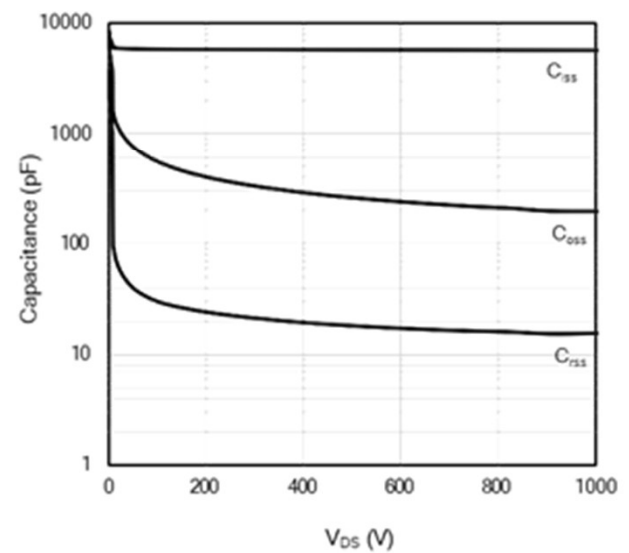


Figure 18: Capacitance Characteristics (0 - 1000 V)

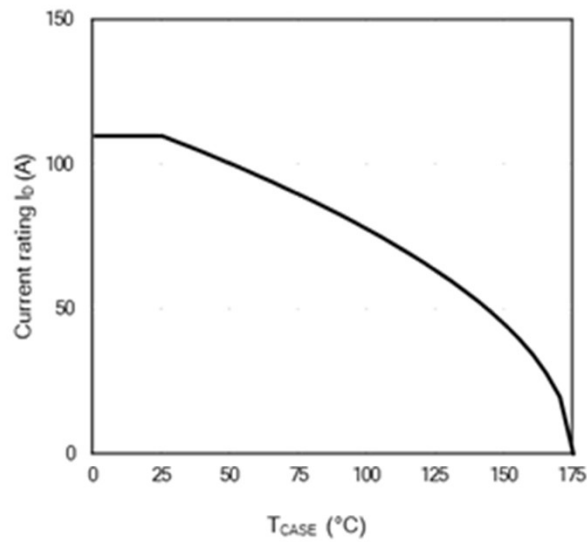


Figure 19: Current De-rating

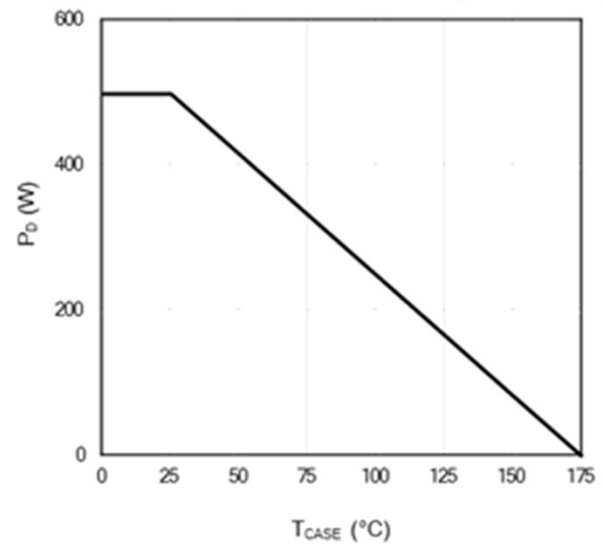


Figure 20: Maximum Power Dissipation Derating vs. Case Temperature

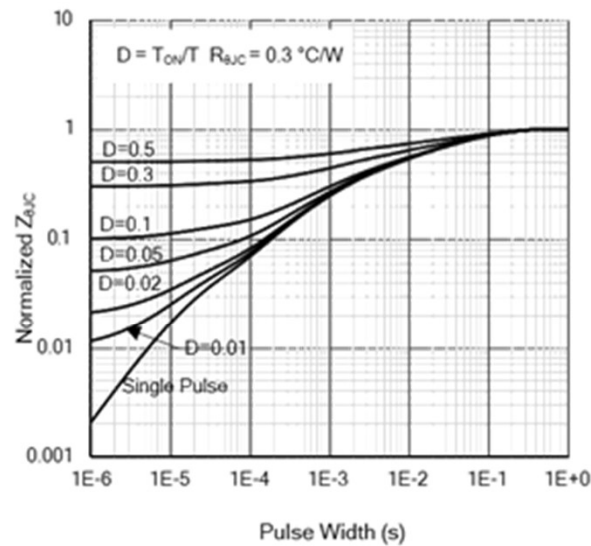


Figure 21: Normalized Maximum Transient Thermal Impedance

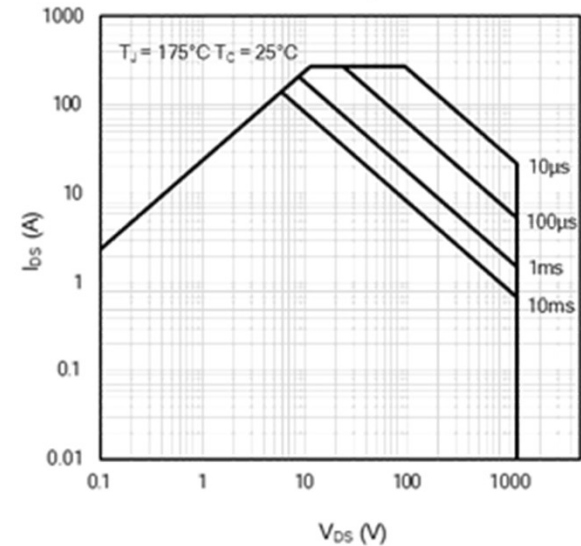


Figure 22: Maximum Forward Biased Safe Operating Area

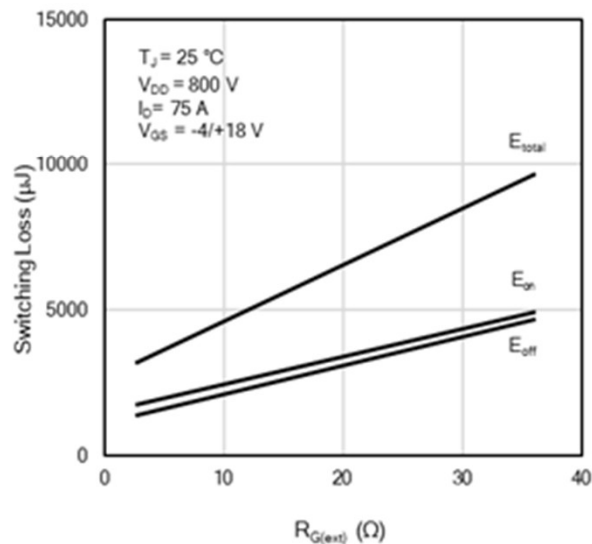


Figure 23: Clamped Inductive Switching Energy vs. $R_{G(ext)}$

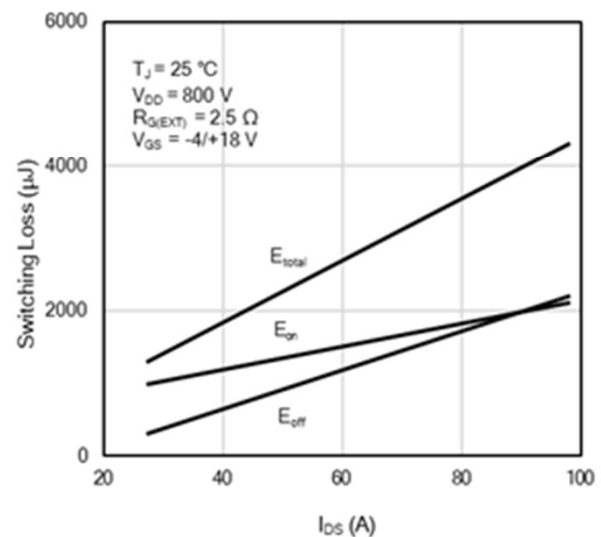


Figure 24: Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800 \text{ V}$)

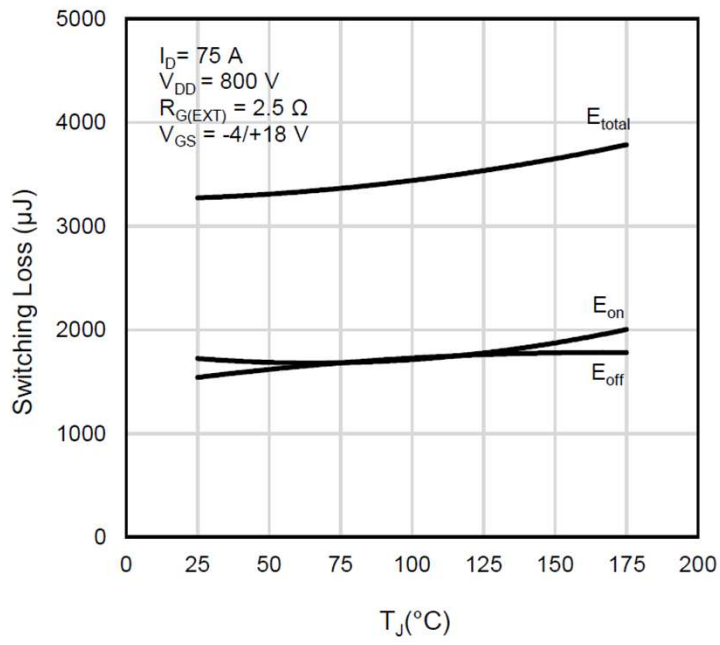


Figure 24: Clamped Inductive Switching Energy vs. T_J

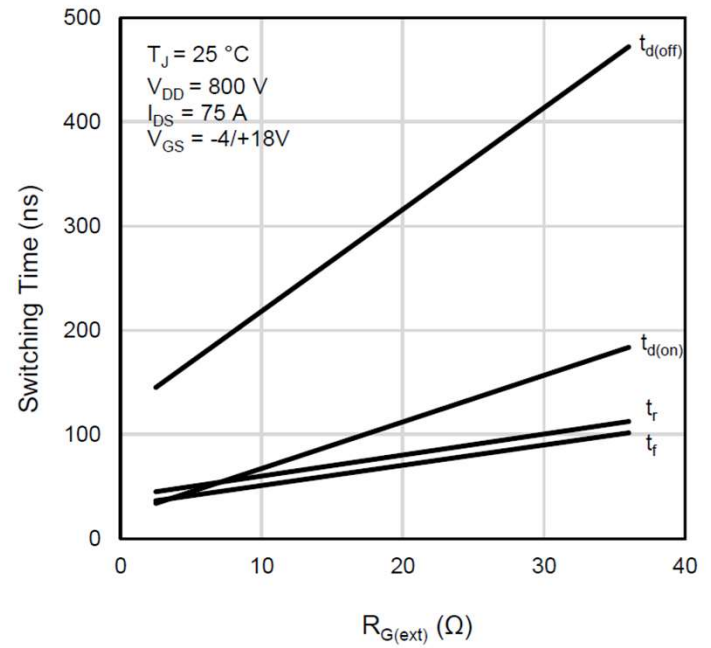
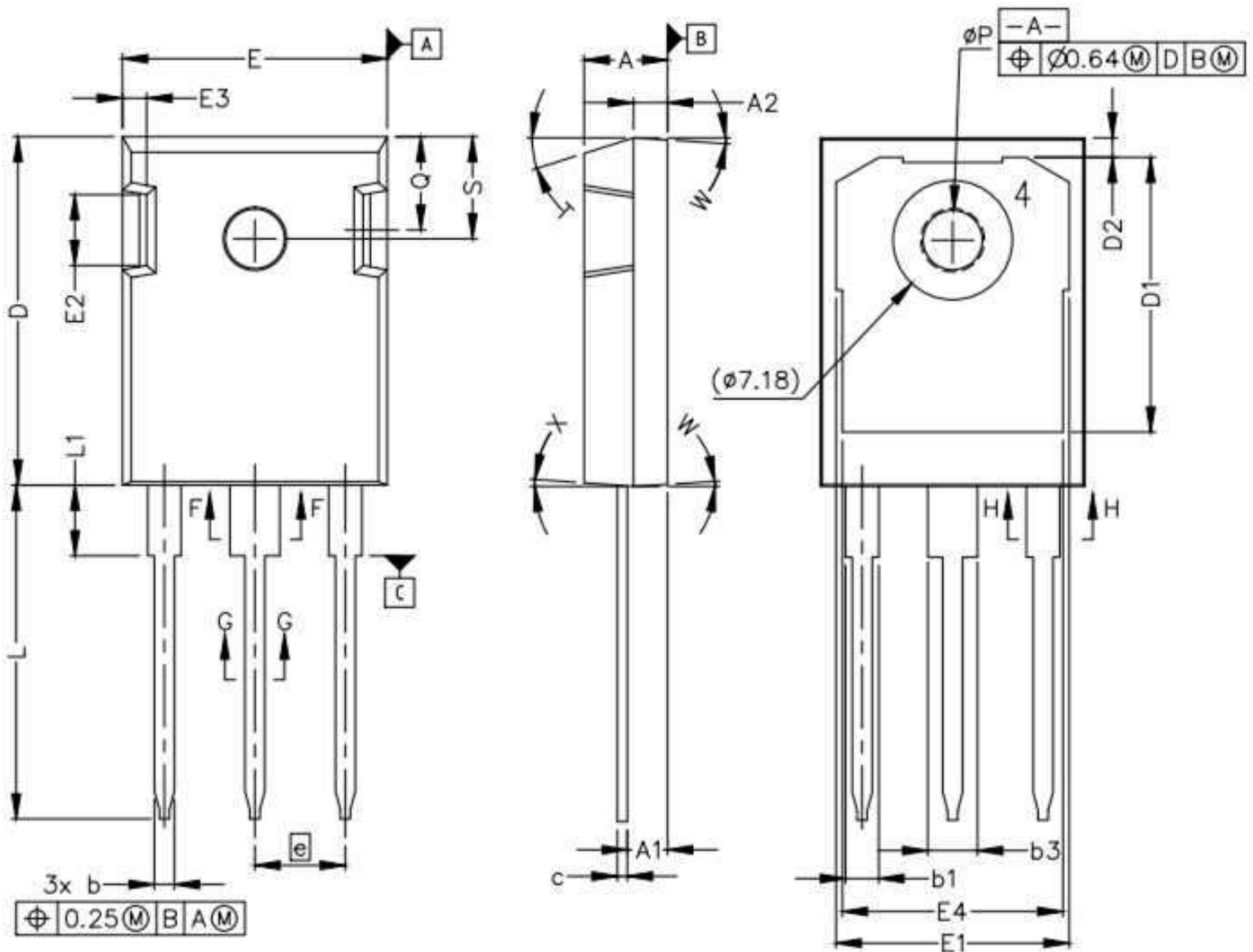


Figure 25: Switching Times vs. $R_{G(ext)}$

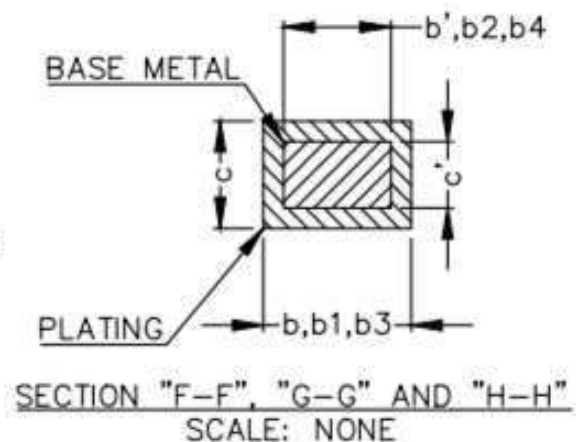
Package Outline: TO-247



NOTE:

1. ALL METAL SURFACES: TIN PLATED EXCEPT AREA OF CUT
2. DIMENSIONING & TOLERANCING CONFIRM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
4. THIS DRAWING WILL MEET ALL DIMENSIONS REQUIREMENT OF JEDEC OUTLINES TO-247 AD.

- 1 - GATE
- 2 - DRAIN (COLLECTOR)
- 3 - SOURCE (EMITTER)
- 4 - DRAIN (COLLECTOR)



Package Outline: TO-247

SYMBOL	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
c	0.55	0.68
D	20.80	21.10
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	5.44 BSC	
N	3	
L	19.81	20.32
L1	4.10	4.40
ØP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	

Marking Information

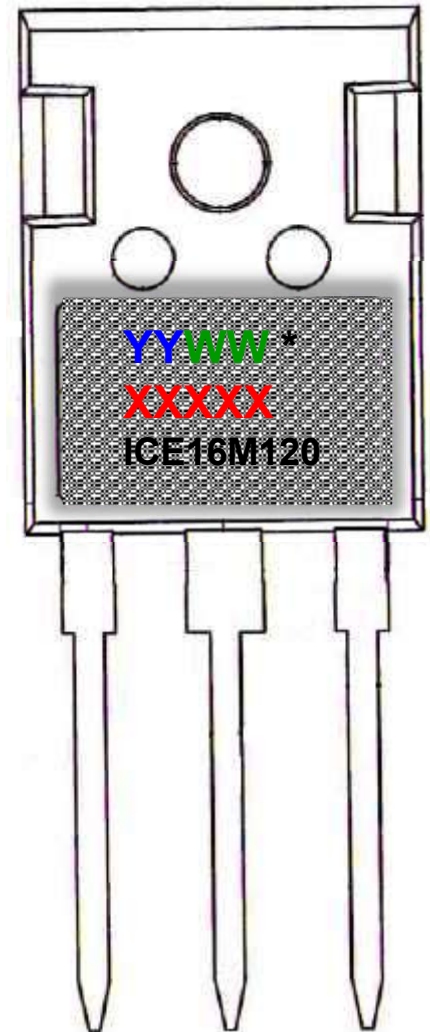
YY = Last two digits of the year

WW = Work week

***** = Site ID

XXXXXX = Lot ID

ICE16M120 = ICE is IceMOS logo and 16M120 is a designated device part number



Disclaimer

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